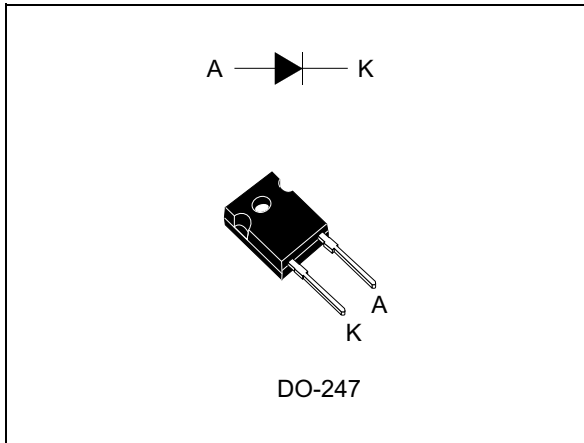


## Turbo 2 ultrafast high voltage rectifier

Datasheet - production data



### Features

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching and conduction losses

### Description

The STTH30ACS06W, which is ST Turbo 2 600 V technology, is suited as boost diode especially in air conditioning equipment for continuous mode interleaved power factor correction.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

**Table 1. Device summary**

Symbol	Value
$I_{F(AV)}$	30 A
$V_{RRM}$	600 V
$T_j$ (max)	175 °C
$V_F$ (typ)	1.45 V
$t_{rr}$ (max)	30 ns

# 1 Characteristics

**Table 2. Absolute ratings (limiting values at  $T_j = 25\text{ °C}$ , unless otherwise specified)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		600	V
$I_{F(RMS)}$	RMS forward current		50	A
$I_{F(AV)}$	Average forward current		30	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal	190	A
$T_{stg}$	Storage temperature range		-65 to +175	°C
$T_j$	Maximum operating junction temperature		+175	°C

**Table 3. Thermal parameters**

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	1.2	°C/W

**Table 4. Static electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-		5	$\mu\text{A}$
		$T_j = 150\text{ °C}$		-	30	300	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 30\text{ A}$	-		2.4	V
		$T_j = 150\text{ °C}$		-	1.45	1.9	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$
2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

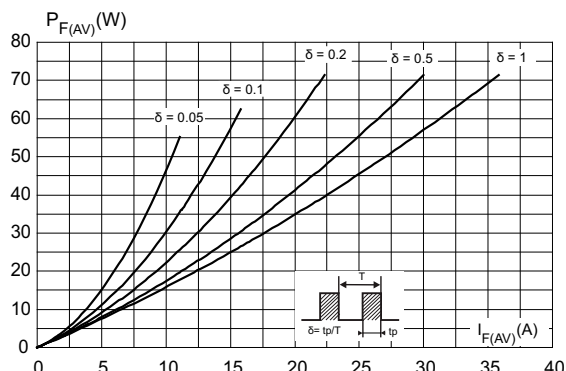
To evaluate the conduction losses use the following equation:

$$P = 1.42 \times I_{F(AV)} + 0.016 \times I_{F(RMS)}^2$$

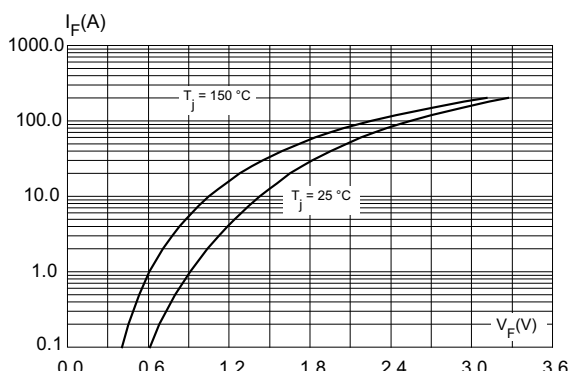
**Table 5. Dynamic electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$T_j = 25\text{ °C}$	$I_F = 0.5\text{ A}$ , $I_{rr} = 0.25\text{ A}$ , $I_R = 1\text{ A}$			30	ns
			$I_F = 1\text{ A}$ , $V_R = 30\text{ V}$ , $di_F/dt = -50\text{ A}/\mu\text{s}$		40	55	ns
$I_{RM}$	Reverse recovery current	$T_j = 125\text{ °C}$	$I_F = 30\text{ A}$ , $di_F/dt = 200\text{ A}/\mu\text{s}$ , $V_R = 400\text{ V}$		7.8	10.5	A
$t_{fr}$	Forward recovery time	$T_j = 25\text{ °C}$	$I_F = 30\text{ A}$ , $di_F/dt = 200\text{ A}/\mu\text{s}$ , $V_{FR} = 2.8\text{ V}$			300	ns
$V_{FP}$	Forward recovery voltage				3.5		V

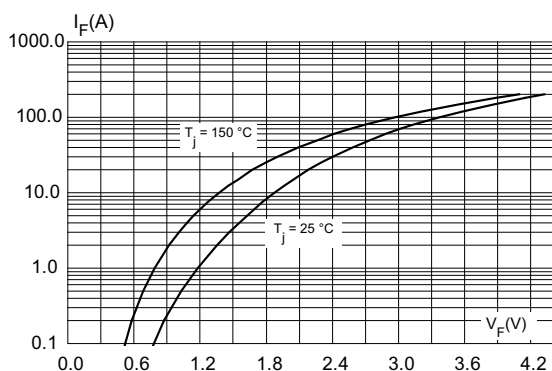
**Figure 1. Average forward power dissipation versus average forward current**



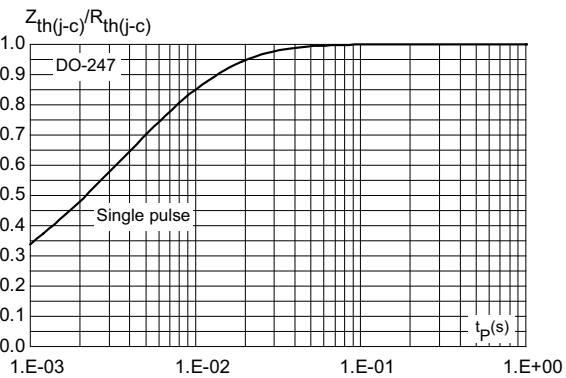
**Figure 2. Forward voltage drop versus forward current (typical values)**



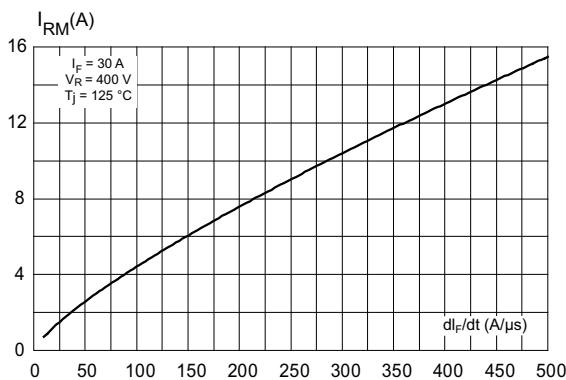
**Figure 3. Forward voltage drop versus forward current (maximum values)**



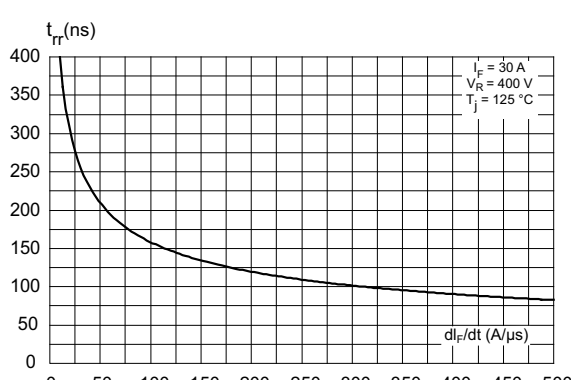
**Figure 4. Relative variation of thermal impedance junction to case versus pulse duration**



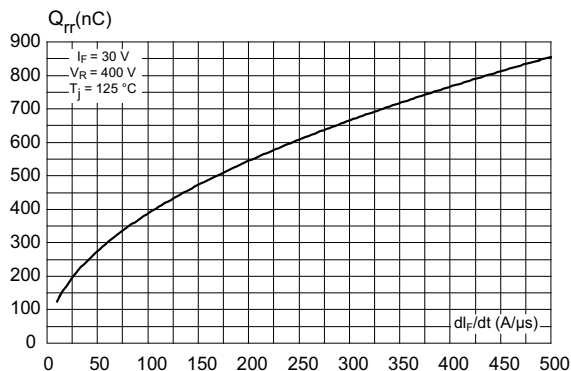
**Figure 5. Peak reverse recovery current versus  $di_F/dt$  (typical values)**



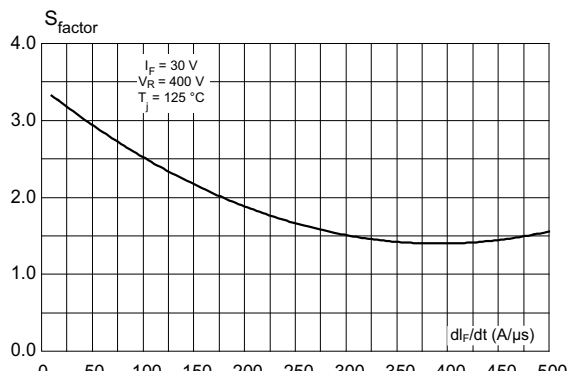
**Figure 6. Reverse recovery time versus  $di_F/dt$  (typical values)**



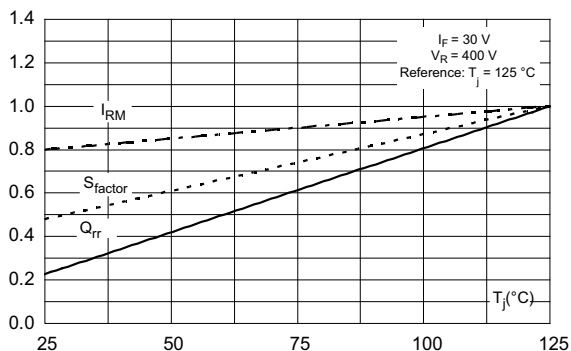
**Figure 7. Reverse recovery charges versus  $di_F/dt$  (typical values)**



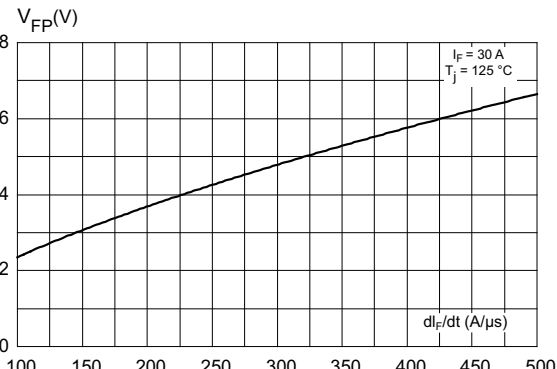
**Figure 8. Softness factor versus  $di_F/dt$  (typical values)**



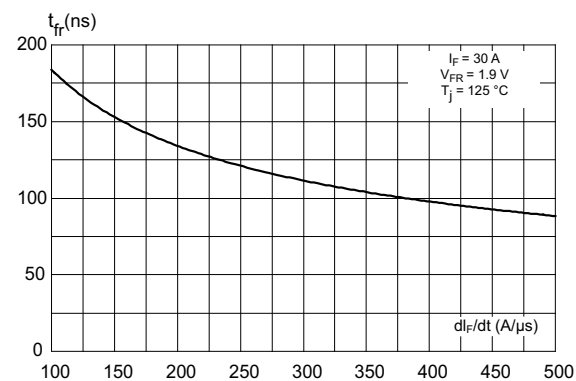
**Figure 9. Relative variations of dynamic parameters versus junction temperature**



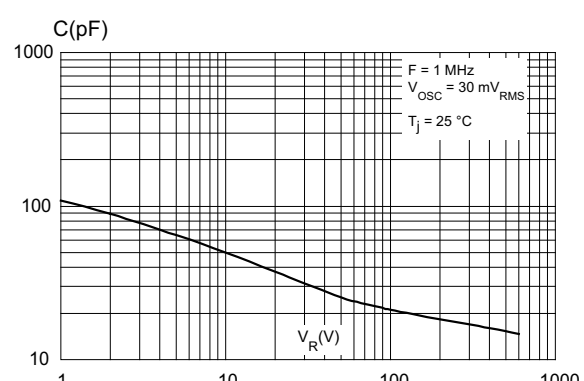
**Figure 10. Transient peak forward voltage versus  $di_F/dt$  (typical values)**



**Figure 11. Forward recovery time versus  $di_F/dt$  (typical values)**



**Figure 12. Junction capacitance versus reverse voltage applied (typical values)**



## 2 Package information

- Epoxy meets UL94, V0
- Cooling method by conduction (C)
- Recommended torque value: 0.8 N·m
- Maximum torque value: 1.0 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 DO-247 package information

Figure 13. DO-247 package outline

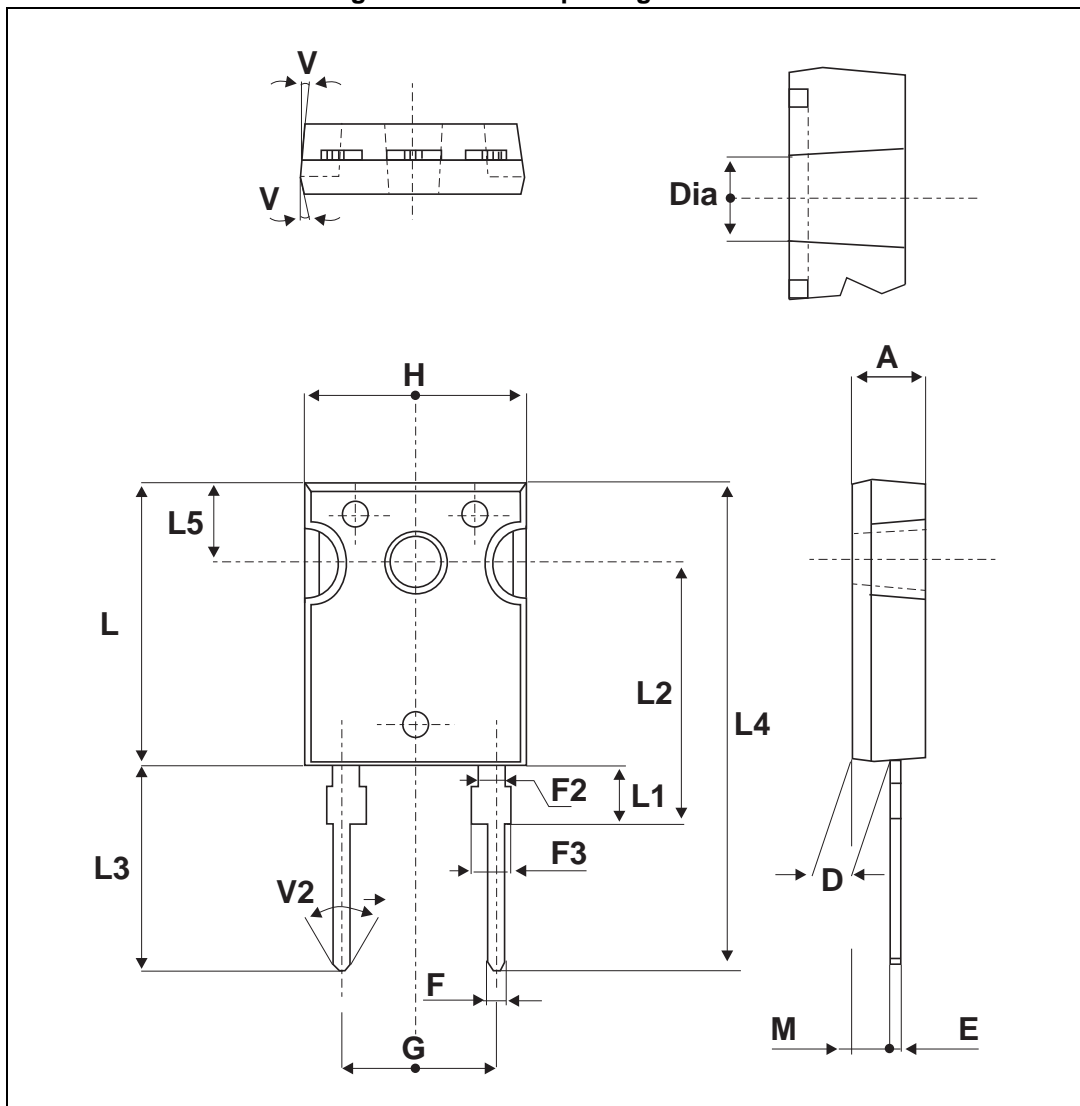


Table 6. DO-247 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
G		10.90			0.429	
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
M	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143

### 3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH30ACS06W	STTH30ACS06W	DO-247	1.8 g	50	Tube

### 4 Revision history

Table 8. Document revision history

Date	Revision	Changes
22-Sep-2015	1	First issue.

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